

LNJ437W84RA

Hight Bright Surface Mounting Chip LED

ESS II Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

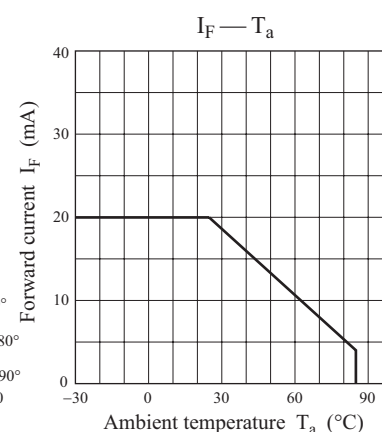
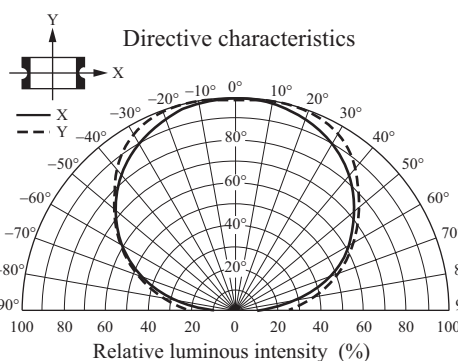
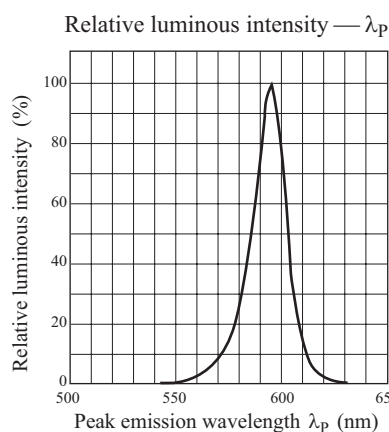
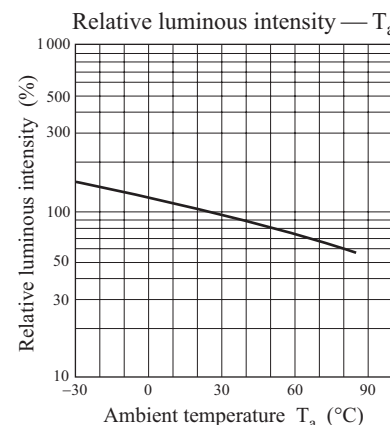
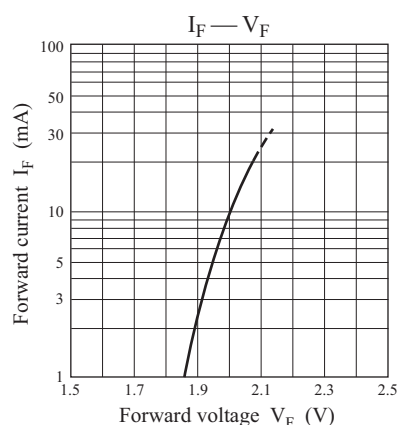
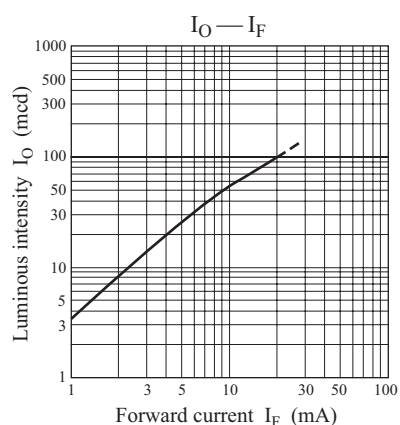
- Amber

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

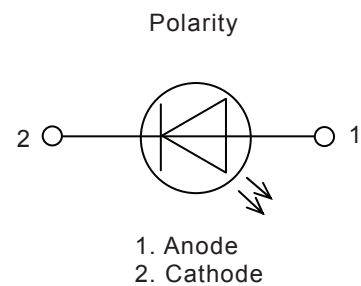
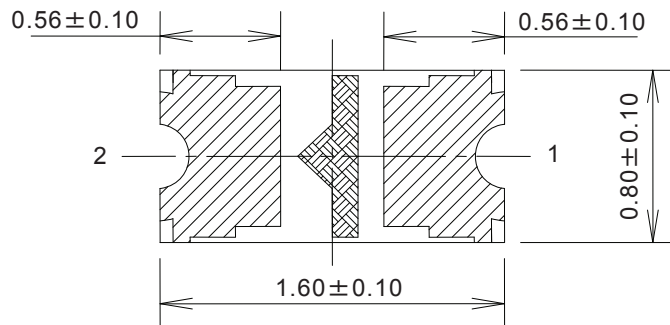
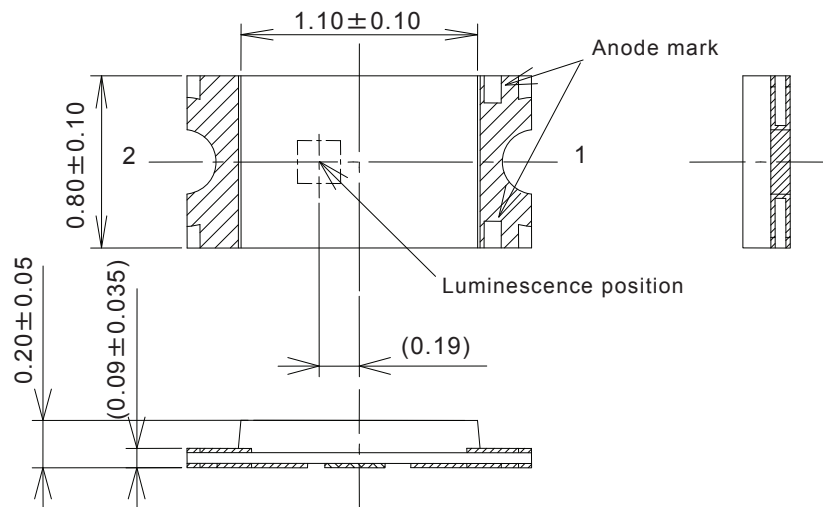
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	I_O	$I_F = 5\text{ mA}$	15.0	25.0	45.0	mcd
Reverse current	I_R	$V_R = 4\text{ V}$			100	μA
Forward voltage	V_F	$I_F = 5\text{ mA}$		1.95	2.30	V
Peak emission wavelength	λ_P	$I_F = 5\text{ mA}$		595		nm
Dominant emission wavelength *2	λ_d	$I_F = 5\text{ mA}$	585	590	595	nm
Spectral half band width	$\Delta\lambda$	$I_F = 5\text{ mA}$		15		nm

Note) *1: Measurement tolerance: $\pm 20\%$

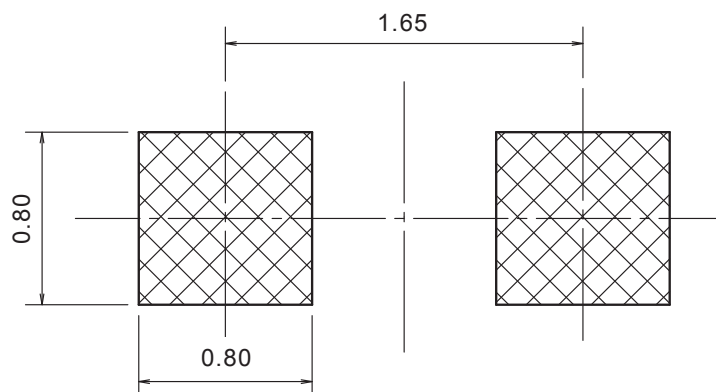
*2: Measurement tolerance: $\pm 2\text{ nm}$



■ Package (Unit: mm)



Recommended Land Layout



(Note1) Electrode projection is not included in the package dimensions.

(Note2) About solder thickness, please examine the products yourself completely.

(Recommended thickness : $t=0.10\text{ mm}\sim 0.15\text{ mm}$)

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